

(0,635 mm) .025"

MEC6-DV SERIES

VERTICAL MICRO EDGE CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?MEC6-DV

Insulator Material:

Black LCP

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over

50μ" (1,27 μm) Ni

Operating Temp Range:

-55°C to +125°C

Insertion Depth:

(4,22 mm) .166" to

(5,66 mm) .223"

Current Rating:

1.7 A per pin

(6 adjacent pins powered)

Voltage Rating:

210 VAC

RoHS Compliant:

Yes

Processing:

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0,10 mm) .004" max (10-50)

(0,15 mm) .006" max (60-70)

Mates with:

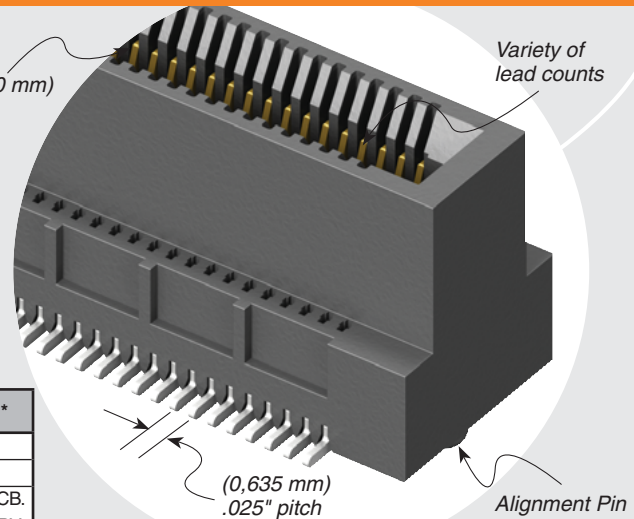
(1,60 mm) .062" thick cards

Mates with (1,60 mm)
.062" thick card

Variety of
lead counts

MEC6-DV 8,65 mm Stack Height	Rated @ 3dB Insertion Loss*
Single-Ended Signaling	7.5 GHz / 15 Gbps
Differential Pair Signaling	7.0 GHz / 14 Gbps

*Performance data includes effects of a non-optimized PCB.
Complete test data available at www.samtec.com?MEC6-DV or contact sig@samtec.com



RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- Locking Clip (Manual placement required)
 - Other platings
- Contact Samtec.

Notes:

While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

Some sizes, styles and options are non-standard, non-returnable.

